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Investment marks the most significant validation of the thin-film thermoelectric technology in Nextreme's history...

NEXTREME RAISES \$8 MILLION IN CORPORATE FUNDING

DURHAM, N.C. (July 8, 2009) — Nextreme Thermal Solutions, the leader in microscale thermal and power management products for the electronics industry, today announced that the company has raised \$8 million in additional Series B financing from undisclosed corporate investors. Nextreme has now raised more than \$21 million in Series B financing and \$35 million since its inception in 2004. The additional funding will be used to expand Nextreme's presence and products for energy harvesting for micro and portable power along with solidifying its position for thermal management products in computing, consumer and mobile markets.

Nextreme offers microscale cooling and thermal energy harvesting solutions that integrate directly into electronic and consumer product packaging. Nextreme's scalable cooling and power generation solutions have the potential to have a major impact on mainstream industries such as automotive, computing, consumer, mobile, and telecommunications. Applications for the technology include: CPU/GPU hot spot cooling, power MOSFET cooling, LED cooling, laser diode cooling, thermal energy scavenging, thermal control in consumer products, power harvesting for sensors, and process control.

Increased functionality in a smaller footprint has been a constant driver in electronics and consumer products throughout the past 30 years. Additionally, the need for improved energy efficiency and micro-scale, distributed power generation capability has emerged as a driver in many applications. These trends have translated into significant thermal and power problems in a host of industries. Nextreme offers one of the few, fundamentally new innovations that addresses both thermal management and power generation in a fully scalable approach. Nextreme's technology is driven by form factor, device performance and cost – all of which are expected to drive adoption of this technology and fuel the company's growth.

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"This funding from corporate investors represents a very significant validation of our company and technology, especially during these challenging times," said Jesko von Windheim, CEO of Nextreme. "With our Series B financing now fully in place, the company is well positioned to execute its product development and sales plan over the next two years."

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About Nextreme Thermal Solutions™, Inc.

Nextreme Thermal Solutions designs and manufactures microscale thermal and power management products for the electronics, telecommunications, semiconductor, consumer, and government/aerospace industries. The company uses breakthrough thin-film thermoelectric material to embed cooling, temperature control and power generation capabilities into the widely accepted copper pillar bumping process used in high-volume electronic packaging. Nextreme's headquarters and manufacturing facility are based near Research Triangle Park, North Carolina.

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